

# Winco Kam Chuen Yung

## List of Publications by Year in descending order

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136  
papers

4,279  
citations

87843

38  
h-index

128225

60  
g-index

136  
all docs

136  
docs citations

136  
times ranked

4088  
citing authors

#	ARTICLE	IF	CITATIONS
1	Enhanced thermal conductivity of boron nitride epoxy matrix composite through multi-modal particle size mixing. <i>Journal of Applied Polymer Science</i> , 2007, 106, 3587-3591.	1.3	272
2	Preparation and properties of hollow glass microsphere-filled epoxy-matrix composites. <i>Composites Science and Technology</i> , 2009, 69, 260-264.	3.8	215
3	Lifetime Estimation of High-Power White LED Using Degradation-Data-Driven Method. <i>IEEE Transactions on Device and Materials Reliability</i> , 2012, 12, 470-477.	1.5	148
4	Embedded components in printed circuit boards: a processing technology review. <i>International Journal of Advanced Manufacturing Technology</i> , 2005, 25, 350-360.	1.5	131
5	Predicting long-term lumen maintenance life of LED light sources using a particle filter-based prognostic approach. <i>Expert Systems With Applications</i> , 2015, 42, 2411-2420.	4.4	123
6	Effect of additions of ZrO <sub>2</sub> nano-particles on the microstructure and shear strength of Sn-Ag-Cu solder on Au/Ni metallized Cu pads. <i>Microelectronics Reliability</i> , 2011, 51, 2306-2313.	0.9	105
7	Microstructure, thermal analysis and hardness of a Sn-Ag-Cu-1wt% nano-TiO <sub>2</sub> composite solder on flexible ball grid array substrates. <i>Microelectronics Reliability</i> , 2011, 51, 975-984.	0.9	104
8	Study on the properties of the epoxy matrix composites filled with thermally conductive AlN and BN ceramic particles. <i>Journal of Applied Polymer Science</i> , 2010, 118, 2754-2764.	1.3	101
9	Physics-of-Failure-Based Prognostics and Health Management for High-Power White Light-Emitting Diode Lighting. <i>IEEE Transactions on Device and Materials Reliability</i> , 2011, 11, 407-416.	1.5	96
10	Microstructure, kinetic analysis and hardness of Sn-Ag-Cu-1wt% nano-ZrO <sub>2</sub> composite solder on OSP-Cu pads. <i>Journal of Alloys and Compounds</i> , 2011, 509, 3319-3325.	2.8	88
11	Thermal performance of high brightness LED array package on PCB. <i>International Communications in Heat and Mass Transfer</i> , 2010, 37, 1266-1272.	2.9	86
12	Ink-jet printing and camera flash sintering of silver tracks on different substrates. <i>Journal of Materials Processing Technology</i> , 2010, 210, 2268-2272.	3.1	82
13	Modeling Young's Modulus of Polymer-layered Silicate Nanocomposites Using a Modified Halpin-Tsai Micromechanical Model. <i>Journal of Reinforced Plastics and Composites</i> , 2006, 25, 847-861.	1.6	81
14	The influence of addition of Al nano-particles on the microstructure and shear strength of eutectic Sn-Ag-Cu solder on Au/Ni metallized Cu pads. <i>Journal of Alloys and Compounds</i> , 2010, 506, 216-223.	2.8	76
15	A Review of Prognostic Techniques for High-Power White LEDs. <i>IEEE Transactions on Power Electronics</i> , 2017, 32, 6338-6362.	5.4	76
16	XPS investigation of the chemical characteristics of Kapton films ablated by a pulsed TEA CO <sub>2</sub> laser. <i>Surface and Coatings Technology</i> , 2002, 153, 210-216.	2.2	75
17	Effect of graphene doping on microstructural and mechanical properties of Sn-8Zn-3Bi solder joints together with electromigration analysis. <i>Journal of Alloys and Compounds</i> , 2013, 580, 162-171.	2.8	72
18	XPS investigation of Upilex-S polyimide ablated by 355 nm Nd:YAG laser irradiation. <i>Applied Surface Science</i> , 2001, 173, 193-202.	3.1	70

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19	Enhanced redshift of the optical band gap in Sn-doped ZnO free standing films using the sol-gel method. <i>Journal Physics D: Applied Physics</i> , 2009, 42, 185002.	1.3	70
20	Influence of SrTiO <sub>3</sub> nano-particles on the microstructure and shear strength of Sn-Ag-Cu solder on Au/Ni metallized Cu pads. <i>Journal of Alloys and Compounds</i> , 2011, 509, 1885-1892.	2.8	66
21	A study of the heat-affected zone in the UV YAG laser drilling of CFRP materials. <i>Journal of Materials Processing Technology</i> , 2002, 122, 278-285.	3.1	64
22	A life-cycle assessment for eco-redesign of a consumer electronic product. <i>Journal of Engineering Design</i> , 2011, 22, 69-85.	1.1	64
23	Effect of AlN content on the performance of brominated epoxy resin for printed circuit board substrate. <i>Journal of Polymer Science, Part B: Polymer Physics</i> , 2007, 45, 1662-1674.	2.4	61
24	Influence of small amount of Al and Cu on the microstructure, microhardness and tensile properties of Sn-9Zn binary eutectic solder alloy. <i>Journal of Alloys and Compounds</i> , 2009, 481, 167-172.	2.8	61
25	Effect of nano Ni additions on the structure and properties of Sn-9Zn and Sn-Zn-3Bi solders in Au/Ni/Cu ball grid array packages. <i>Materials Science and Engineering B: Solid-State Materials for Advanced Technology</i> , 2009, 162, 92-98.	1.7	59
26	355nm Nd:YAG laser ablation of polyimide and its thermal effect. <i>Journal of Materials Processing Technology</i> , 2000, 101, 306-311.	3.1	58
27	Electrochemically reduced graphene oxide/carbon nanotubes composites as binder-free supercapacitor electrodes. <i>Journal of Power Sources</i> , 2016, 311, 144-152.	4.0	57
28	UV Nd:YAG laser ablation of copper: chemical states in both crater and halo studied by XPS. <i>Applied Surface Science</i> , 2003, 217, 170-180.	3.1	56
29	Effect of the filler size and content on the thermomechanical properties of particulate aluminum nitride filled epoxy composites. <i>Journal of Applied Polymer Science</i> , 2010, 116, 225-236.	1.3	55
30	Introduction to graphene electronics - a new era of digital transistors and devices. <i>Contemporary Physics</i> , 2013, 54, 233-251.	0.8	52
31	Study of PEDOT-PSS in carbon nanotube/conducting polymer composites as supercapacitor electrodes in aqueous solution. <i>Journal of Electroanalytical Chemistry</i> , 2014, 728, 140-147.	1.9	50
32	Thermal investigation of a high brightness LED array package assembly for various placement algorithms. <i>Applied Thermal Engineering</i> , 2014, 63, 105-118.	3.0	46
33	An investigation into welding parameters affecting the tensile properties of titanium welds. <i>Journal of Materials Processing Technology</i> , 1997, 63, 759-764.	3.1	45
34	Laser direct patterning of a reduced-graphene oxide transparent circuit on a graphene oxide thin film. <i>Journal of Applied Physics</i> , 2013, 113, .	1.1	44
35	Interfacial microstructure and shear strength of Ag nano particle doped Sn-9Zn solder in ball grid array packages. <i>Microelectronics Reliability</i> , 2009, 49, 746-753.	0.9	42
36	Prerequisites for achieving gold adsorption by multiwalled carbon nanotubes in gold recovery. <i>Chemical Engineering Science</i> , 2014, 107, 58-65.	1.9	40

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37	Prognostics of lumen maintenance for High power white light emitting diodes using a nonlinear filter-based approach. Reliability Engineering and System Safety, 2014, 123, 63-72.	5.1	40
38	Prognostics of Chromaticity State for Phosphor-Converted White Light Emitting Diodes Using an Unscented Kalman Filter Approach. IEEE Transactions on Device and Materials Reliability, 2014, 14, 564-573.	1.5	39
39	The values of TQM in the revised ISO 9000 quality system. International Journal of Operations and Production Management, 1997, 17, 221-230.	3.5	37
40	Thermal Management for Boron Nitride Filled Metal Core Printed Circuit Board. Journal of Composite Materials, 2008, 42, 2615-2627.	1.2	37
41	Theoretical and experimental study on the kerf profile of the laser micro-cutting NiTi shape memory alloy using 355 nm Nd:YAG. Smart Materials and Structures, 2005, 14, 337-342.	1.8	36
42	Effect of nano Al <sub>2</sub> O <sub>3</sub> additions on the microstructure, hardness and shear strength of eutectic Sn-9Zn solder on Au/Ni metallized Cu pads. Microelectronics Reliability, 2010, 50, 2051-2058.	0.9	36
43	Synthesis of submicron sized silver powder for metal deposition via laser sintered inkjet printing. Journal of Materials Science, 2009, 44, 154-159.	1.7	35
44	Study on ceramic/polymer composite fabricated by laser cutting. Materials Chemistry and Physics, 2002, 75, 147-150.	2.0	32
45	Investigation of small Sn-3.5Ag-0.5Cu additions on the microstructure and properties of Sn-8Zn-3Bi solder on Au/Ni/Cu pads. Journal of Alloys and Compounds, 2010, 489, 678-684.	2.8	32
46	Effect of small Sn-3.5Ag-0.5Cu additions on the structure and properties of Sn-9Zn solder in ball grid array packages. Microelectronic Engineering, 2009, 86, 2347-2353.	1.1	29
47	Electrochemically reduced graphene oxides/nanostructured iron oxides as binder-free electrodes for supercapacitors. Electrochimica Acta, 2017, 231, 125-134.	2.6	28
48	The laser dressing of resin-bonded CBN wheels by a Q-switched Nd: YAG laser. International Journal of Advanced Manufacturing Technology, 2003, 22, 541-546.	1.5	27
49	Nd:YAG laser drilling in epoxy resin/AlN composites material. Composites Part A: Applied Science and Manufacturing, 2007, 38, 2055-2064.	3.8	26
50	Relevance and feasibility of the existing social LCA methods and case studies from a decision-making perspective. Journal of Cleaner Production, 2018, 171, 690-703.	4.6	26
51	Investigation of laser surface alloying of copper on high nickel austenitic ductile iron. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2002, 333, 223-231.	2.6	25
52	Life cycle assessment of two personal electronic products—a note with respect to the energy-using product directive. International Journal of Advanced Manufacturing Technology, 2009, 42, 415-419.	1.5	24
53	Thermomigration and electromigration in Sn58Bi ball grid array solder joints. Journal of Materials Science: Materials in Electronics, 2010, 21, 1090-1098.	1.1	24
54	Size Control and Characterization of Sn-Ag-Cu Lead-Free Nanosolders by a Chemical Reduction Process. Journal of Electronic Materials, 2012, 41, 313-321.	1.0	23

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55	Fabrication of epoxy-montmorillonite hybrid composites used for printed circuit boards via in-situ polymerization. <i>Advanced Composite Materials</i> , 2006, 15, 371-384.	1.0	21
56	A return on investment analysis of applying health monitoring to LED lighting systems. <i>Microelectronics Reliability</i> , 2015, 55, 527-537.	0.9	21
57	Lumen Degradation Lifetime Prediction for High-Power White LEDs Based on the Gamma Process Model. <i>IEEE Photonics Journal</i> , 2019, 11, 1-16.	1.0	21
58	Laser induced activation of circuit lines and via-holes on AlN for electroless metal plating. <i>Applied Surface Science</i> , 2011, 257, 6601-6606.	3.1	20
59	Optimal Design of Life Testing for High-Brightness White LEDs Using the Six Sigma DMAIC Approach. <i>IEEE Transactions on Device and Materials Reliability</i> , 2015, 15, 576-587.	1.5	20
60	Laser ablation of Upilex-S polyimide: influence of laser wavelength on chemical structure and composition in both ablated area and halo. <i>Surface and Coatings Technology</i> , 2001, 145, 186-193.	2.2	19
61	Application of value delivery system (VDS) and performance benchmarking in flexible business process reengineering. <i>International Journal of Operations and Production Management</i> , 2003, 23, 300-315.	3.5	19
62	Effect of Ag micro-particles content on the mechanical strength of the interface formed between Sn <sup>62</sup> Zn binary solder and Au/Ni/Cu bond pads. <i>Microelectronic Engineering</i> , 2009, 86, 2086-2093.	1.1	19
63	Degradation mechanism beyond device self-heating in high power light-emitting diodes. <i>Journal of Applied Physics</i> , 2011, 109, 094509.	1.1	19
64	XPS investigation on Upilex-S polyimide ablated by pulse TEA CO <sub>2</sub> laser. <i>Applied Surface Science</i> , 2001, 180, 280-285.	3.1	17
65	UV laser micromachining of piezoelectric ceramic using a pulsed Nd:YAG laser. <i>Applied Physics A: Materials Science and Processing</i> , 2004, 78, 415-421.	1.1	17
66	Modeling the Etching Rate and Uniformity of Plasma-Aided Manufacturing Using Statistical Experimental Design. <i>Materials and Manufacturing Processes</i> , 2006, 21, 899-906.	2.7	17
67	Eco-redesign of a personal electronic product subject to the energy-using product directive. <i>International Journal of Production Research</i> , 2012, 50, 1411-1423.	4.9	17
68	Heat dissipation performance of a high-brightness LED package assembly using high-thermal conductivity filler. <i>Applied Optics</i> , 2013, 52, 8484.	0.9	17
69	High repetition rate effect on the chemical characteristics and composition of Upilex-S polyimide ablated by a UV Nd:YAG laser. <i>Surface and Coatings Technology</i> , 2002, 160, 1-6.	2.2	16
70	Thermomigration and electromigration in Sn <sub>8</sub> Zn <sub>3</sub> Bi solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2011, 22, 217-222.	1.1	16
71	Influence of small Sb nanoparticles additions on the microstructure, hardness and tensile properties of Sn <sup>62</sup> Zn binary eutectic solder alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2012, 23, 1427-1434.	1.1	16
72	The effects of pulse plating parameters on copper plating distribution of microvia in PCB manufacture. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2003, 26, 106-109.	1.6	15

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73	Size Effect of AlN on the Performance of Printed Circuit Board (PCB) Material-brominated Epoxy Resin. <i>Journal of Composite Materials</i> , 2006, 40, 567-581.	1.2	15
74	Studies on laser ablation of low temperature co-fired ceramics (LTCC). <i>International Journal of Advanced Manufacturing Technology</i> , 2009, 42, 696-702.	1.5	14
75	A finite element model and experimental analysis of PTH reliability in rigid-flex printed circuits using the Taguchi method. <i>International Journal of Fatigue</i> , 2012, 40, 84-96.	2.8	14
76	Prognostics-based qualification of high-power white LEDs using L <sup>4</sup> o <sub>v</sub> y process approach. <i>Mechanical Systems and Signal Processing</i> , 2017, 82, 206-216.	4.4	14
77	System level reliability assessment for high power light-emitting diode lamp based on a Bayesian network method. <i>Measurement: Journal of the International Measurement Confederation</i> , 2021, 176, 109191.	2.5	14
78	Investigation of corrosion behavior of high nickel ductile iron by laser surface alloying with copper. <i>Scripta Materialia</i> , 2001, 44, 2747-2752.	2.6	13
79	Fabrication of Polymer Silver Conductor Using Inkjet Printing and Low Temperature Sintering Process. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2008, 31, 291-296.	1.6	13
80	An environmental assessment framework with respect to the Requirements of Energy-using Products Directive. <i>Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture</i> , 2008, 222, 643-651.	1.5	13
81	Prerequisite for maximizing thermal conductivity of epoxy laminate using filler. <i>Journal of Materials Science: Materials in Electronics</i> , 2013, 24, 1095-1104.	1.1	13
82	Corrosion resistance enhancement of Ni-resist ductile iron by laser surface alloying. <i>Scripta Materialia</i> , 2001, 44, 651-657.	2.6	12
83	Development of epoxy matrix composite with both high thermal conductivity and low dielectric constant via hybrid filler systems. <i>Journal of Applied Polymer Science</i> , 2010, 116, 518-527.	1.3	12
84	Multiresponse Optimization of Surface Plasma Treatment Using Taguchi Method. <i>Materials and Manufacturing Processes</i> , 2010, 25, 1001-1011.	2.7	12
85	Preparation and properties of aluminum nitride filled epoxy composites: Effect of filler characteristics and composite processing conditions. <i>Journal of Applied Polymer Science</i> , 2013, 127, 3456-3466.	1.3	12
86	Mesostructured composite coating on SAE 1045 carbon steel synthesized in situ by laser surface alloying. <i>Materials Letters</i> , 2002, 56, 680-684.	1.3	11
87	Frequency-tripled Nd:YAG laser ablation in laser structuring process. <i>Optics and Lasers in Engineering</i> , 2006, 44, 815-825.	2.0	11
88	Life cycle assessment study of an integrated desktop device -comparison of two information and communication technologies: Desktop computers versus all-in-ones. <i>Journal of Cleaner Production</i> , 2017, 156, 828-837.	4.6	11
89	Impact of plasma etching on fabrication technology of liquid crystal polymer printed circuit board. <i>Journal of Materials Science: Materials in Electronics</i> , 2010, 21, 954-962.	1.1	10
90	Fabrication and adhesion performance of gold conductive patterns on silicon substrate by laser sintering. <i>Applied Surface Science</i> , 2011, 258, 478-481.	3.1	10

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91	An integrated model for manufacturing process improvement. Journal of Materials Processing Technology, 1996, 61, 39-43.	3.1	9
92	Pulsed UV laser ablation of a liquid crystal polymer. International Journal of Advanced Manufacturing Technology, 2005, 26, 1231-1236.	1.5	9
93	Selective laser processing of ink-jet printed nano-scaled tin-clad copper particles. Applied Physics A: Materials Science and Processing, 2010, 101, 393-397.	1.1	9
94	Model scenario for integrated environmental product assessment at the use of raw materials stage of a product. Resources, Conservation and Recycling, 2010, 54, 841-850.	5.3	9
95	Thermal Investigation and Placement Design of High-Brightness LED Array Package on PCB for Uniform Illuminance. Journal of Electronic Packaging, Transactions of the ASME, 2011, 133, .	1.2	8
96	A Green Approach to Synthesis of Nanoparticles of Sn&ndash;3.0Ag&ndash;0.5Cu Lead-Free Solder Alloy. Materials Transactions, 2012, 53, 1770-1774.	0.4	8
97	Experimental investigation of 355nm Nd:YAG laser ablation of RCCRin PCB. Circuit World, 1999, 25, 13-17.	0.7	7
98	Rapid prototyping of polymer-based MEMS devices using UV YAG laser. Journal of Micromechanics and Microengineering, 2004, 14, 1682-1686.	1.5	7
99	A study of microvias produced by laser-assisted seeding mechanism in blind via hole plating of printed circuit board. International Journal of Advanced Manufacturing Technology, 2004, 24, 474-484.	1.5	7
100	The effect of waveform for pulse plating on copper plating distribution of microvia in PCB manufacture. International Journal of Advanced Manufacturing Technology, 2004, 23, 245-248.	1.5	7
101	Feasibility of the 248Ånm Excimer laser in the laser structuring of fine circuit lines on printed circuit board. International Journal of Advanced Manufacturing Technology, 2007, 33, 1149-1158.	1.5	7
102	Anomaly detection for chromaticity shift of high power white LED with mahalanobis distance approach. , 2012, , .		7
103	Copper Direct Drilling With TEA<tex>\$\hbox CO_2\$</tex>Laser in Manufacture of High-Density Interconnection Printed Circuit Board. IEEE Transactions on Electronics Packaging Manufacturing, 2006, 29, 145-149.	1.6	6
104	Envelope probability and EFAST-based sensitivity analysis method for electronic prognostic uncertainty quantification. Microelectronics Reliability, 2015, 55, 1384-1390.	0.9	6
105	A stepped composite methodology to redesign manufacturing processes through reâ€engineering and benchmarking. International Journal of Operations and Production Management, 1997, 17, 375-388.	3.5	5
106	Near-threshold ultraviolet-laser ablation of Kapton film investigated by x-ray photoelectron spectroscopy. Journal of Materials Research, 2003, 18, 53-59.	1.2	5
107	Studies on laser ablation of low temperature coâ€fired ceramics (LTCC). Microelectronics International, 2007, 24, 27-33.	0.4	5
108	A prerequisite to achieving high performance polymer/inorganic thin film diodes. Solid State Communications, 2010, 150, 1725-1728.	0.9	5

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109	Chelating Resin for Removal of Nickel Impurities from Gold Electroplating Solutions. Industrial & Engineering Chemistry Research, 2013, 52, 2418-2424.	1.8	5
110	The degradation of elastic properties of aluminum alloy 2024T3 due to strain damage. Scripta Materialia, 1997, 38, 231-238.	2.6	4
111	Environmental impact of two electrical products with reference to the energy-using products directive. International Journal of Sustainable Engineering, 2012, 5, 86-90.	1.9	4
112	Dynamic high potential treatment with dilute acids for lifting the capacitive performance of carbon nanotube/conducting polymer electrodes. Journal of Electroanalytical Chemistry, 2015, 758, 125-134.	1.9	4
113	Evolution of Microstructure, Texture and Mechanical Properties for Multilayered Al Matrix Composites by Accumulative Roll Bonding. Materials, 2021, 14, 5576.	1.3	4
114	Surface characterization of pre-treated copper foil used for PCB lamination. Journal of Adhesion Science and Technology, 2007, 21, 363-377.	1.4	3
115	Effect of nano Ni additions on the structure and properties of Sn-9Zn and Sn-8Sn-3Bi solder in ball grid array packages. , 2008, , .		3
116	A study of critical processing technologies of liquid crystal polymer printed circuit board for high speed application. Journal of Applied Polymer Science, 2010, 116, 2348-2358.	1.3	3
117	Thermal performance and placement design of LED array package on PCB. , 2012, , .		3
118	Selective patterning and scribing of Ti thin film on glass substrate by 532 nm picosecond laser. Applied Physics A: Materials Science and Processing, 2012, 107, 351-355.	1.1	3
119	The control of the thin-plate welds geometry and microstructure. Journal of Materials Processing Technology, 1997, 63, 802-805.	3.1	2
120	Analysis of process parameters of laser structuring with Taguchi method. Applied Physics A: Materials Science and Processing, 2010, 101, 385-392.	1.1	2
121	Studied on the Microfluidic Chip Based on the Kapton by Excimer Laser Ablation. Key Engineering Materials, 0, 458, 81-86.	0.4	2
122	Correlating Interconnect Stress Test and Accelerated Thermal Cycling for Accessing the Reliabilities of High Performance Printed Circuit Boards. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 2005-2017.	1.4	2
123	Chemorheological study of phosphorylated flame retardant epoxies. Plastics, Rubber and Composites, 2011, 40, 25-31.	0.9	2
124	Influence of Photolithography on the Cross-Sectional Shape of Polysiloxane as an Optical Waveguide Material on Printed Circuit Boards. Journal of Electronic Materials, 2013, 42, 3494-3501.	1.0	2
125	Time-variant reliability analysis of ship grillage structure. , 2015, , .		2
126	Quality and Reliability of High Aspect-Ratio Blind Microvias Formed by Laser-Assisted Seeding Mechanism in PCB. IEEE Transactions on Electronics Packaging Manufacturing, 2004, 27, 115-124.	1.6	1



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127	The effect of plasma etching process on rigid flex substrate for electronic packaging application. , 2009, , .		1
128	Fabrication of Biodegradable Polymeric Micro-Analytical Devices Using a Laser Direct Writing Method. Advanced Materials Research, 2010, 136, 53-58.	0.3	1
129	A practical design of reliability and performance test for portable lithium-ion batteries. , 2015, , .		1
130	Optimizing control dynamic complexity and production schedule. International Journal on Interactive Design and Manufacturing, 2019, 13, 47-58.	1.3	1
131	A Temperature Model For Ultrasonic Measurement of Titanium Welds. HKIE Transactions, 1995, 2, 33-37.	1.9	0
132	Effect of small Sn-Ag-Cu additions on structure and properties of Sn-Zn-Bi solder/BGA during as-soldered and as-aged conditions. , 2009, , .		0
133	Rheological Characterization and Statistical Modeling of Resin Flow of No-flow Polyimide Prepreg in Rigid-Flex Printed Circuit Lamination. Journal of Composite Materials, 2011, 45, 171-185.	1.2	0
134	Additive Manufacturing of Cobalt-Based Organic Ferromagnetic Materials. , 2016, , .		0
135	Study of Electrochemical Performance of Li-Ion Batteries Based on Simultaneous Measurement of a Three-Electrode System. , 2016, , .		0
136	Multi-objective Ant Colony Optimization for Production Line Balance and Dynamic Complexity. , 2019, , .		0